Device Material Content

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Package: 121 csfBGA
Total Device Weight 70.07 **Milligrams**

Package Code: MG121
Products: LIFCL-17

Assembly: ASEK
Size (mm): 6 x 6
Lead pitch (mm): 0.5
MSL: 3
Reflow max (ºC): 260

	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	10.24%	7.174	10.24%	7.1740	Silicon chip	7440-21-3	100.00%	Die size: 4.085 x 3.767mm
Mold Compound	34.73%	24.338	4.17%	2.9206	Epoxy Resins	-	12.00%	Hitachi G311SAC
			1.74%	1.2169	Phenol Resins	-	5.00%	
			26.05%	18.2535	Silica(Amorphous)	7631-86-9	75.00%	
			2.61%	1.8254	Aluminum Hydroxide	21645-51-2	7.50%	
			0.17%	0.1217	Carbon Black	1333-86-4	0.50%	
Substrate	11.61%	8.133	3.71%	2.6026	BT Resins	-	32.00%	MGC CCL-HL832NS
			7.89%	5.5304	Glass fiber	65997-17-3	68.00%	
Foil	19.82%	13.891	19.82%	13.8861	Copper (Cu)	7440-50-8	99.97%	
			0.01%	0.0042	OSP	-	0.03%	
Solder Mask	1.02%	0.716	0.24%	0.1684	Solvent naphtha (petroleum)	64742-94-5	23.52%	PFR800 AUS 320
			0.06%	0.0421	Naphthalene	91-20-3	5.87%	
			0.15%	0.1053	Phosphinoxide derivative	-	14.70%	
			0.15%	0.1053	Talc (containing no asbestiform fibers)	14807-96-6	14.70%	
			0.18%	0.1262	Dipropylene glycol monomethyl Ether	34590-94-8	17.63%	
			0.15%	0.1053	Epoxy Resin	85954-11-6	14.70%	
			0.09%	0.0636	Barium Sulfate	7727-43-7	8.88%	
Bump	1.73%	1.214	0.62%	0.4350	Tin (Sn)	7440-31-5	35.83%	
			0.01%	0.0080	Silver (Ag)	7440-22-4	0.66%	
			0.66%	0.4610	Nickel (Ni)	7440-02-0	37.97%	
			0.44%	0.3100	Copper (Cu)	7440-50-8	25.54%	
RDL	1.04%	0.727	0.11%	0.0780	Titanium (Ti)	7440-32-6	10.73%	
			0.93%	0.6490	Copper (Cu)	7440-50-8	89.27%	
UBM	0.55%	0.387	0.11%	0.0780	Titanium (Ti)	7440-32-6	20.16%	
			0.44%	0.3090	Copper (Cu)	7440-50-8	79.84%	
Repassivation polyimide	0.11%	0.078	0.061%	0.0429	N-Methyl-2-pyrrolidone	872-50-4	55.00%	HD4000E
			0.006%	0.0039	Proprietary Monomer	-	5.00%	
			0.001%	0.0004	Methanol	67-56-1	0.50%	
			0.044%	0.0308	Non regulated ingredients	-	39.50%	
Solder Balls	19.14%	13.410	18.47%	12.9407	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.57%	0.4023	Silver (Ag)	7440-22-4	3.00%	
			0.10%	0.0671	Copper (Cu)	7440-50-8	0.50%	

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